

RECEIVED  
FEB -6 2003  
TECHNOLOGY CENTER 2800

PATENT APPLICATION

**RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 2826**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

15/01/03  
JN/EPW  
2/12/03

Nobuaki HASHIMOTO

Group Art Unit: 2826

Application No.: 09/856,924

Examiner: T. N. Tran

Filed: May 30, 2001

Docket No.: 109681

For: SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME,  
CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

**AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116**

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the November 6, 2002 Office Action, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please cancel claims 20-32 without prejudice to or disclaimer of the subject matter contained therein. Applicant reserves the right to file a Divisional Application to pursue these claims.

Please replace claim 1 as follows:

1. (Twice Amended) A semiconductor device comprising:

*CJ*  
a substrate including a plurality of holes and a surface over which an interconnecting pattern is formed, part of the interconnecting pattern being superposed over the holes;